

WHAT IS CLAIMED IS:

1. An IC socket for a fine pitch IC package, comprising
a socket body having an opening for guiding the IC package
5 to a predetermined position,

an insulation base having a plurality of through-holes
corresponding to the external terminals of the IC package,
contact pins placed in the through-holes respectively,
and

10 a cover member for applying a predetermined pressure
to bring the external terminals of the IC package and the
contact pins into contact with one another,

wherein each of the contact pins is formed with the
first plunger including a terminal portion to be in contact
15 with an external terminal of the IC package, a wider portion
whose width is larger than the width of the terminal portion
and a shaft whose width is equal to or smaller than the
width of the terminal portion, a coil spring permitting
the shaft to be inserted therein, and a second plunger,
20 having a U-shape section, to be connected to the contact
terminal of external circuit.

2. An IC socket for a fine pitch IC package as claimed
in claim 1, wherein a bottom end of the shaft of the first
25 plunger is provided with a projection that is always kept
in contact with the second plunger.

3. An IC socket for a fine pitch IC package as claimed in claim 1, wherein the first plunger and the second plunger are formed from a thin metal sheet by a press work.

5 4. An IC socket for a fine pitch IC package, comprising a socket body having an opening for guiding the IC package to a predetermined position,

an insulation base having a plurality of through-holes corresponding to the external terminals of the IC package,
10 contact pins to be placed in the through-holes, and a cover member for applying a predetermined pressure to bring the external terminals of the IC package and the contact pins into contact with one another,

wherein each of the contact pins is formed with a plunger,
15 including a terminal portion to be in contact with the external terminal of the IC package, a wider portion whose width is larger than the width of the terminal portion and a shaft whose width is equal to or smaller than the terminal portion, and a coil spring unit including a coil spring
20 permitting the shaft to be inserted therein and a tight-winding coil portion following the coil spring.

5. An IC socket for a fine pitch IC package as claimed in claim 4, wherein the bottom end of the shaft of the plunger
25 is provided with a projection that is always in contact with the tight-winding coil portion of the coil spring unit.

6. An IC socket for a fine pitch IC package as claimed in claim 4, wherein the plunger is formed from a thin metal sheet by the press work.

5 7. An IC socket for a fine pitch IC package, comprising a socket body having an opening for guiding the IC package to a predetermined position,

an insulation base having a plurality of through-holes corresponding to the external terminals of the IC package,
10 contact pins to be placed in the through-holes, and a cover member for applying a predetermined pressure to bring the external terminals of the IC package and the contact pins into contact with one another,

wherein each of the contact pins is formed with a first
15 plunger including a first terminal portion to be in contact with the external terminal of the IC package and a wider portion whose width is larger than the width of the first terminal portion and in which a fitting indent opening downward is disposed, and a second plunger including a
20 second terminal portion to be in contact with the contact terminal of external circuit and a pair of legs extending upward from the second terminal portion to fit in the fitting indent and having elastically deformable bent portions provided at the middles of the legs.

25

8. An IC socket for a fine pitch IC package as claimed in claim 7, wherein the first plunger and the second plunger

are formed from a thin metal sheet by the press work.

9. An IC socket for a fine pitch IC package, comprising
a socket body having an opening for guiding the IC package
5 to a predetermined position,

an insulation base having a plurality of through-holes
corresponding to the external terminals of the IC package,
contact pins to be placed in the through-holes, and
a cover member for applying a predetermined pressure
10 to bring the external terminals of the IC package and the
contact pins into contact with one another,

wherein each of the contact pins is formed with a first
plunger including a first terminal portion to be in contact
with the external terminal of the IC package, a wider portion
15 whose width is larger than the width of the first terminal
portion and provided with a pair of legs extending
downwardly from two sides of the wider portion, a second
plunger including a second terminal portion to be connected
with the contact terminal of the external circuit and an
20 extended portion extending upwardly from the second
terminal portion and slidably interposed between the pair
of legs of the wider portion and a coil spring interposed
between the pair of legs.

25 10. An IC socket for a fine pitch IC package as claimed
in claim 9, wherein the first plunger and the second plunger
are formed from a thin metal sheet by the press work.